

CHO-TRT725

TEST REPORT

Thermal Performance vs. Contact Pressure for THERMFLOWä T725 Phase-Change Material

Prepared by:

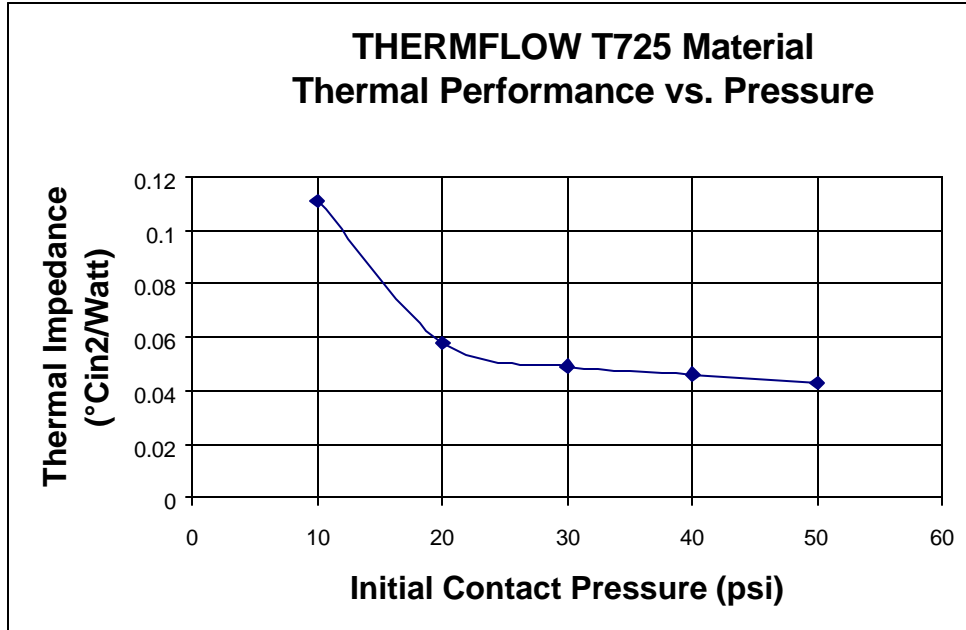
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THERMFLOWä T725 Phase-Change Material

Thermal Performance vs. Contact Pressure

ASTM D5470 test procedure was performed to determine the thermal performance of Chomerics' THERMFLOW T725 material versus the amount of contact pressure applied. The T725 material tested was batch number 2969, manufactured on October 22nd, 1999, from roll #4. As expected, increasing the contact pressure results in improved thermal transfer. The lack of a fiberglass carrier allows the T725 material to have as thin a bond line as possible.



CONTACT PRESSURE (psi)	THERMAL IMPEDANCE (°C in ² / Watt)
10	0.1
20	0.06
30	0.05
40	0.05
50	0.04